

Supermicro evolutionary 4U twin architecture and PUE-optimized solutions"



Agenda

SUPERMICR®

Supermicro Company Profile

Supermicro's innovative platforms

Low power Atom Solution

MicroCloud Solutions

FatTwin solutions























Supermicro Overview

SUPERMICR



SMC Inc., HQ San Jose, CA SMC BV, The Netherlands



Founded in 1993, HQ- San Jose, CA / NASDAQ: SMCI



Global Footprint: >70 Countries

Production: US, EU and Asia Production facilities

Engineering: 70% of workforce in engineering (30% growth through recession)

Market Share: #1 Server Channel (SMCI enables ~10% of global server market)

Brand Equity: Growing public profile since 2007 IPO

<u>Partners:</u> 500+ Global System Integrator, VAR and Distributor Partners

Corporate Focus: Energy Efficiency, Earth-friendly, Technology Innovation

























Low Power Atom and Space-Saver Server



SuperServer® SYS-5017A-EF

Power and Space-saver Server

KEY FEATURES

Processor

Intel Atom SoC S1260 CPU, 2C/4T, 32nm (Centerton, 8.5W)

Chipset

N/A (System on Chip)

Memory

Up to 8GB DDR3-1333 ECC SO-DIMMs

Expansion

1x PCI 32-bit 3.3V on riser

External I/O

VGA, Serial, 2x GbE i350AM2, 2x USB 3.0

Storage

4 x SATA3, 6Gb/s ports 2x 3.5" fixed SATA3 w/ RAID options (opt 4x 2.5")

Power Supply

200W Power Supply

Additional

Disk-on-Module (DOM) power connector IPMI 2.0 on dedicated LAN port Supports 2.5" HDD/SSD via optional bracket







rear view

- Space-efficient, compact design 9.8" (249mm)
- Fast to build and deploy
- Great for gateway, file-serving, security
- Remote management, RAID options
- 3 year limited warranty, 24 hour support hotline



5017A-EF Drive Options





Up to 2x 3.5"











Up to 4x 2.5"

RAID options



00044-0N



00051-0N

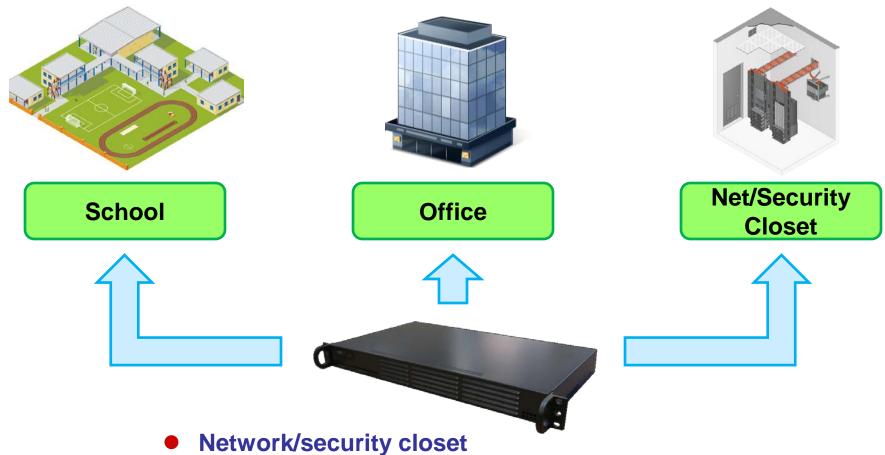
- **Up to 4 drives**
- Use bracket for 2.5"
- RAID 0, 1, 5, 10 3.





SUPERMICR® Confidential

Where do these servers fit?



- Home, office, other building or facility
- **Anywhere** you need a compact server function



5017A-EF Selling Points

- Leveraging the Mobile ECC Promotion
 - Atom ECC is part of Intel's high profile launch
 - SMC is leader in servers, so this is an emerging opportunity
- Entry level SMB Server/Storage Solution
 - Enhance I/O performance for entry level NAS, rackmount SMB Storage/Server
 - VT-x Intel 64 bit CPU Virtualization and Hyper-Thread Technologies
- Energy efficient
 - CPU is S1260 2C/4T, 2.0GHz ,8.5W, TDP up to 60W typically
 - High density for low-end hosting and sub-entry tiers
- IPMI 2.0 for remote management
 - Matrox VGA with KVM function using Nuvoton NCT6776F
- Many built-in features
 - SATA DOM support, port headers, fast multi-port networking, and much more to support a wide range of applications





MicroCloud SuperServer solutions.

High Density, Enterprise Performance, Cost Effective UP servers



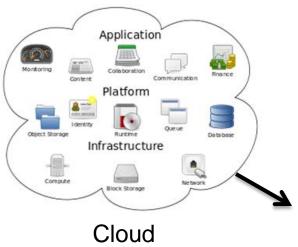
What is MicroCloud?

- SuperServer with a large number of UP nodes to maximize shared resource utilization and provide a cost-effective alternative to typical rackmount servers without any compromise.
- Evolutionary design to expand Supermicro's presence in high-efficiency Cloud computing infrastructure deployments



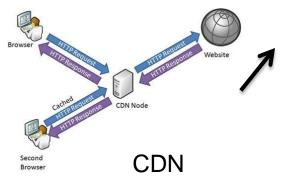
Market Opportunity

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(intel)

Ivy Bridge

SYS-5037MC-H8TRF









- High Density with 8 Nodes in 3U
- Intel IvyBridge E3-1200 V2 CPU upto 95W
- up to 32GB DDR3 1600 MHz
- 1 x PCI-E Gen3 x8 LP slot
- Cost effective solution





















intel

Ivy Bridge

SYS-5037MC-H86RF











- High Density with 8 Nodes in 3U
- Intel Ivy Bridge E3-1200 V2 CPU to 95W
- up to 32GB DDR3 1600 MHz
- 2 x 3.5" hot-swap SAS/SATA HDD with selected AOC card
- 1 x PCI-E Gen3 x8 LP slot





















X9 Romley MicroCloud[™]



SYS-5037MR-H8TRF











- **MicroLP Cards**

- High Density with 8 Nodes in 3U
- Intel Romley E5-2600 CPU to 130W
- Up to 128GB DDR3 1600Mhz
- 2 x 3.5" hot-swap SATA HDD
- 1 x PCI-E Gen3 x8 LP slot
- Flexible SMC MicroLP card





2nd Generation MicroCloudTM



SYS-5037MC-H12TRF



MicroLP Cards







- High Density with12 Nodes in 3U
- Intel E3-1200 v2 CPU support up to 69W/(87W)
- up to 32 GB VLP DDR3 1600Mhz
- 2 x 3.5" or 4 x 2.5" SATA HDD
- Flexible SMC MicroLP card



A+ Server AS-3012MA-H12TRF

- Motherboard: H8SME-F
- Mid Tower Chassis: CSE-939H-R1K63B



12 x Hot-Pluggable UP Nodes

Key Features

- High-density, Enterprise Performance, Cost-effective,
 Multi-node UP server
- Redundant 80Plus Platinum Level Power Supplies
- Dedicated LAN for System management (IPMI 2.0)

Processor Support & Chipset

4/8 -core AMD Socket **AM3+** Opteron™ 3000 Series

Memory Capacity

Up to 32 GB R/UDDR3 ECC 1066/1333/1600 Mhz in 8 DIMMs

Expansion Slots

One Micro LP slot (Gb,10Gb,IB..)

I/O ports

1x VGA ,COM2 ,USB port (via dongle)

1 dedicated LAN for system management (IPMI2.0)

Drive Bays

2x 3.5" or 4 x2.5" internal drive bays

Power Supply

1620W Redundant Platinum Level

System Cooling

4-pin PWM fans w/ Optimal Fan Speed Control

Applications

- **SMB** application
- **❖** File & Print Server
- Mail server













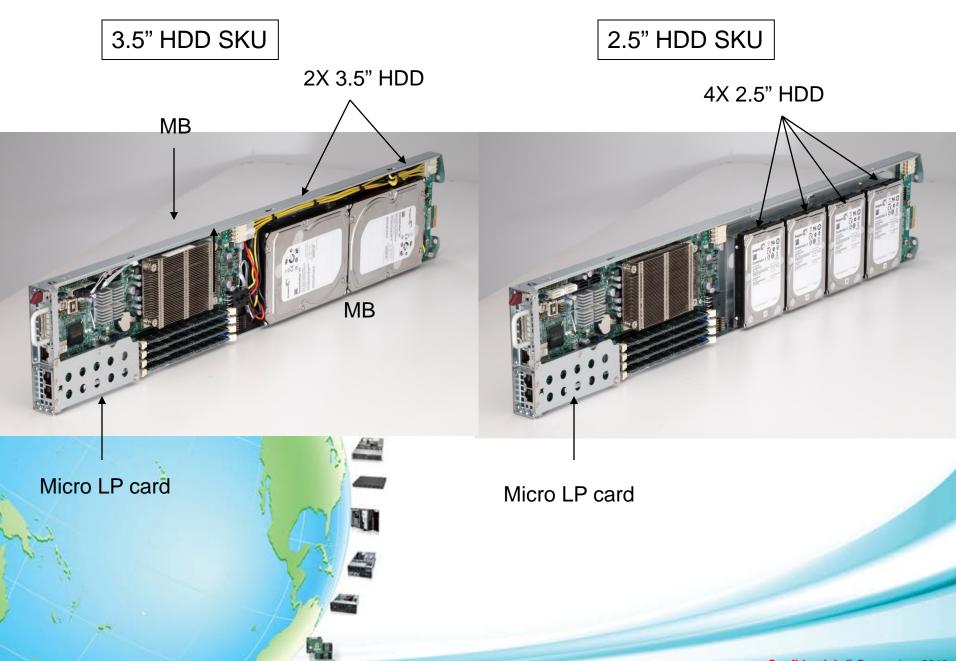








MicroCloud Server with 3.5"HDD/2.5"HDD skus





Fat TwinTM Server Solution



Twin Revolution

High-Capacity Scalable Multi-Node Computing Solutions

High-density compute Improved storage capacity Better expansion High efficiency





2012

- ✓ Extremely high power efficiency
- ✓ High storage capacity
- √ High MIC/Xeon phi capacity
- √ Highly configurable computing
- √ for both compute and I/O
- ✓ Excellent expansion capability
- ✓ Accessibility and maintainability



Confidential

Why choose Fat Twin™

Confidential

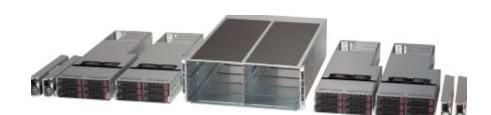
- Optimized design for different applications
 - Datacenter/ Cloud/ HPC applications
 - Science/ Research/ GPU application
 - File server/ Storage server
 - General server/ Enterprise server



- Efficient air cooling design (PUE ~1.1)
- 135W XEON CPU support up to 35°C
- 130W XEON CPU support up to 47°C



- Flexible and configurable node structure
- Hot-plug MB node access from front side, easy for maintenance
- Resource sharing in design, tooling, inventory and components for cost effectiveness
- Support standard rack
- ► High density, high performance and lower power consumption
 - High density: support DP 16 DIMM & 8 x 3.5" hot swap HDD per 1U
 - High density: support DP 16 DIMM & 3 GPU per 1U or 8 GPU per 2U
 - High efficiency design for MB and sharing cooling with 3 -10% less power usage
 - High operation temperature support (47°C Free-air-cooling, PUE~1.1)

















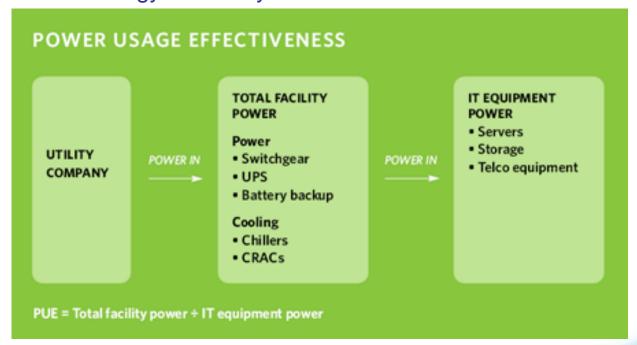






Define PUE

- PUE is determined by dividing the amount of power entering a data center by the power used to run the computer infrastructure within it.
- PUE was created by members of the Green Grid, an industry group focused on data center energy efficiency.























Twin Architecture

47C

135W

4/8 Nodes

2.74 TFlops

128 TBytes





Supermicro Fat Twin Solutions

FatTwin Rear I/O



4U with 4-node/8-node
PUE optimized –
130W/135W
Flexible
Dense storage 8 HDD/1U
- 2.5"/3.5" SAS/SATA;
More add-on cards

FatTwin Front I/O



4U with 4-node/8-node
PUE optimized –
130W/135W
Front I/O cabling
Redundant hot-plug fans
Cost effective storage

GPU Optimized Front I/O



4U with 4-node
Densest GPU solution
12x PCI-E 3.0 x16 supports
12 Double-Width
GPU/MiC Cards

Hadoop Front I/O

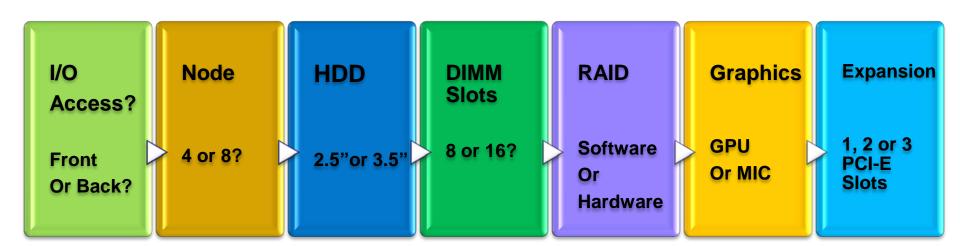


4U with 4-node Lower cost storage for Big Data 12 HDD/1U -3.5" Fixed SAS/SATA Drives.

Standard 19" Racks, Front Access Server Nodes, Industry Standard IPMI 2.0 Highest Efficiency Redundant Power Supply (95%+)



Supermicro FatTwin Decision Tree



Power Supply – 1280 or1600 Watts, Digital Supplies

Wide Choice - 20 Plus Models to choose from

* Hadoop 4Node Cluster also available



4-Node Front I/O

SYS-F627R3-FT/SYS-F627R3-F73

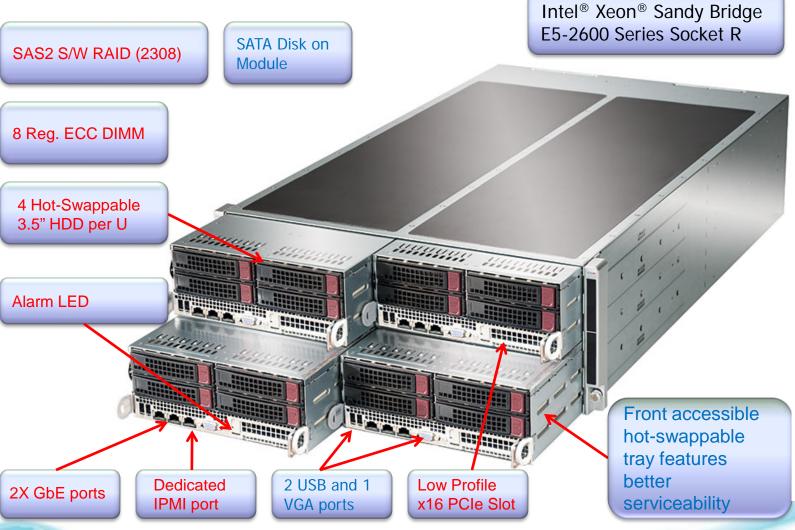
































8-Node Front I/O



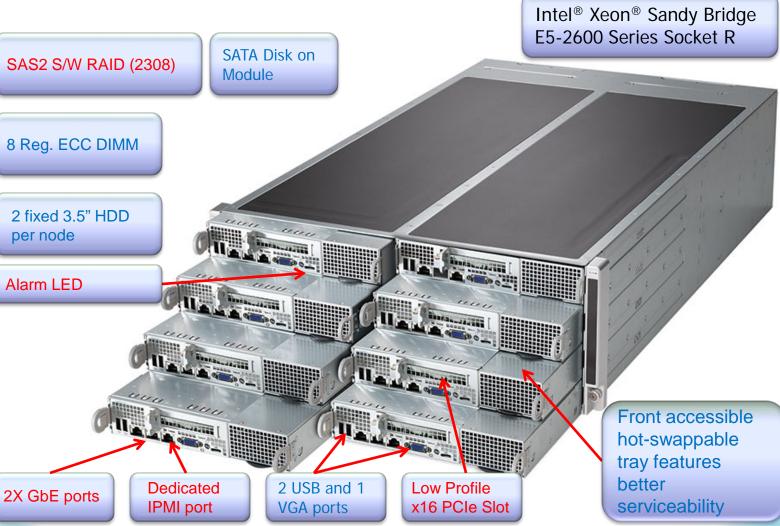
























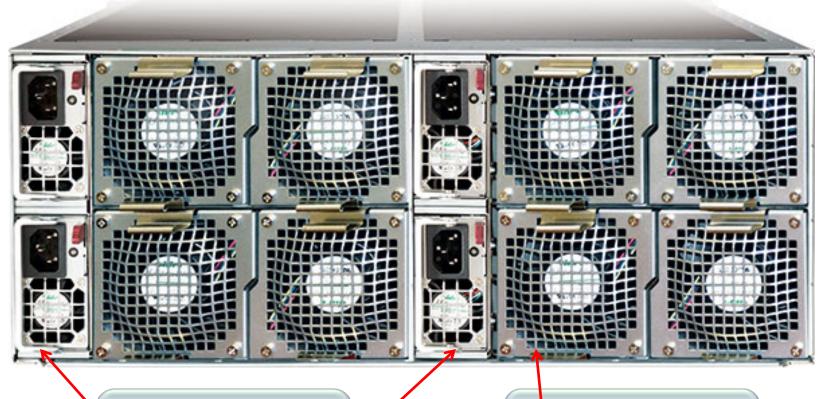








Rear View of Front I/O



1+1 redundant 1620W 94+% PSU Or 1280W 95+% PSU

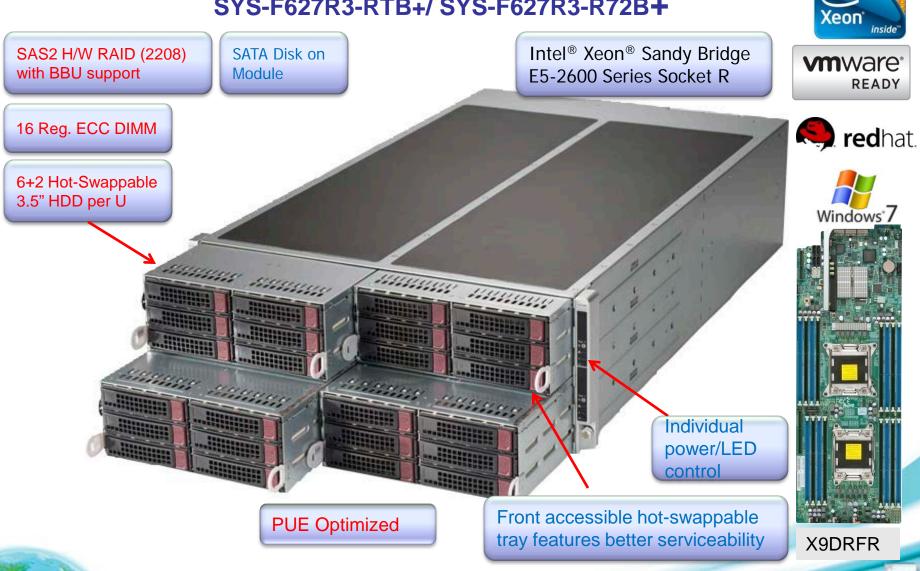
80mm x 80mm hot-swappable shared heavy duty fan



DC Software

4-Node Rear I/O

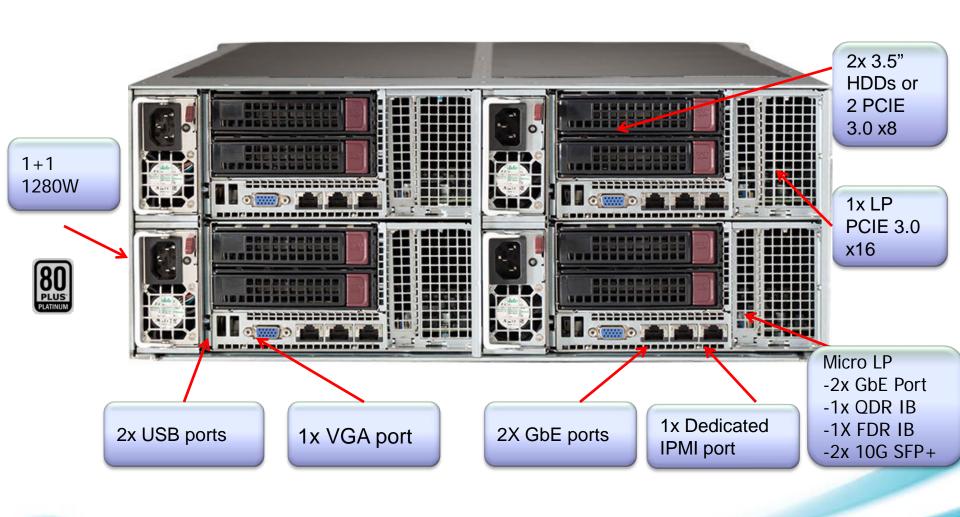
SYS-F627R3-RTB+/ SYS-F627R3-R72B+





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4-Node Rear I/O 8 hot swappable 3.5"HDDs per U

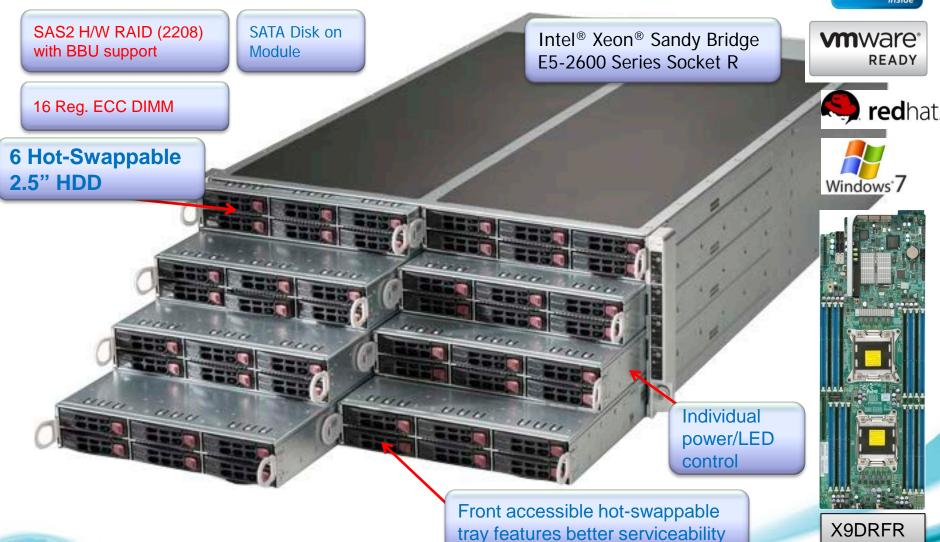




8-Node Rear I/O

SYS-F617R2-RT+/SYS-F617R2-R72+

























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8-Node Rear I/O

SYS-F617R2-RT+/SYS-F617R2-R72+





2x USB Ports

1x VGA Port

1x LP PCI-E 3.0 x16 Micro LP

- -2x GbE Port
- -1x QDR IB
- -1 x FDR IB
- -2x 10G SFP+

2x GbE Ports

1x Dedicated

IPMI Port

















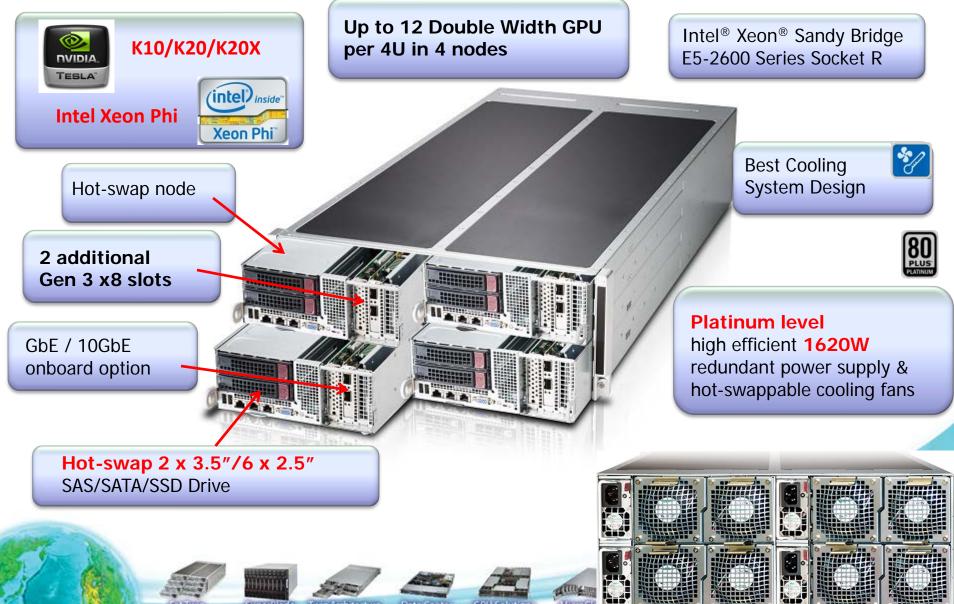




GPU FatTwin Front I/O

SYS-F627G3-FT+





GbE / 10GbE

onboard option

hot-swappable cooling fans

Rear View

Highest Optimized Architecture

Application Optimized

Scale-up and/or Scale-out

Data Center / Cloud / Hadoop

HPC/GPU

Science / Research

Finance / Oil & Gas

Performance Optimized

Maximum Compute & I/O Density

135W High-End CPU

8 Hot-Swap HDD Per 1U

16/24 DIMM Per Node

12 GPU Per Enclosure

FatTwin

Value Optimized

Performance/Watt - Performance/\$

Lower Power Per Node

Shared/Redundant Resources

Platinum/Redundant/Digital Power

TCO Optimized

Free Air Cooling – 1.1 PUE

135W @ 35C

130W @ 47C

Front I/O or Rear I/O Flexibility

Eliminate UPS with optional BBP



Applications



Cloud Computing



Search Engine



Hadoop



Data Center



Engineering



Research



Simulation



Multimedia/Graphics



Enterprise IT



File System



Storage Server



Medical



Oil & Gas Exploration



Financial Simulation



3D Rendering/Gaming



GPGPU Application























Evolutionary Fat Twin Technology

Evolutionary Design in Twin Family Flexibility, Performance, Density... And Lower Power Consumption Modular Design with variety of choices SUPERMICR



Thank you! Any Questions?



